

Chemask® NA High Temperature Solder Masking Agent

Product# CNA8, CNA1

Product Description

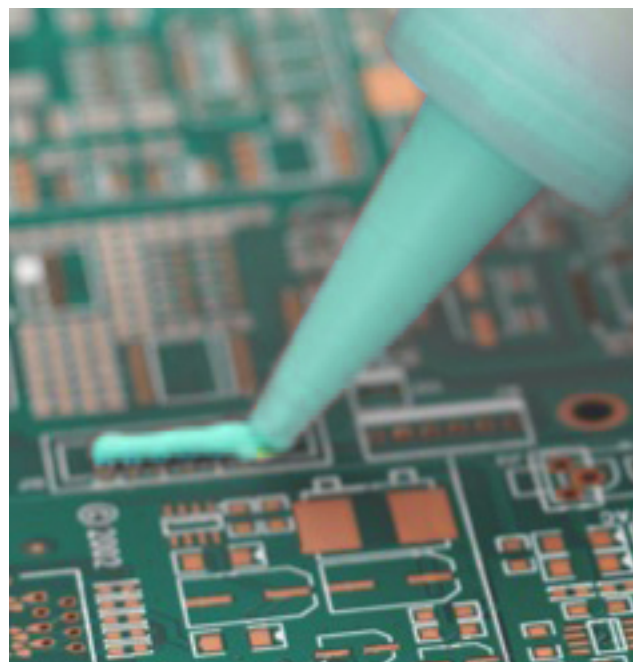
Chemask NA Non-Ammoniated Solder Masking Agent is a fast curing, peelable temporary spot mask formulated for safe use on sensitive metals. It contains high-temperature resistant compounds that protect component-free areas during wave soldering. Chemask NA may be used to protect pins, posts, contacts and edge connections in the solder reflow oven or during conformal coating processes.

- Stable to 550°F (288°C)
- For lead-free or tin/lead processes
- Phthalate-free, low toxicity and environmentally safe
- Compatible with rosin, water soluble fluxes and cleaning solvents
- Dries tack free in 15 minutes
- Goes straight into the pre-heat oven
- Removes easily and leaves no residue
- Non-contaminating, non-staining and non-corrosive
- Compatible with gold, copper, nickel, silver and OSP finishes
- RoHS compliant

Typical Applications

Chemask NA protects:

- Component-free areas during wave and reflow soldering
- Components and pin connectors
- Temperature sensitive components during wave or reflow soldering



Typical Product Data and Physical Properties

Base Material	Synthetic Resin
Color	Green
Odor	Odorless
Flux Compatibility	All types
Process Compatibility	Wave Soldering & Reflow
Solder Compatibility	Lead Free & Tin/Lead
Temperature Stability	550°F/ 288°C
Tack-Free Drying Time (10 mils @ 77°F/25°C)	15 min.
Cure Time (10 mils @ 77°F/25°C)	30 min.
Viscosity (@ 77°F)	20,000 cps
Viscosity Adjusted With	DI water
Flash Point	Nonflammable
Weight/Gallon	8.5 lbs.
Shelflife	2 years
RoHS Compliant	Yes

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Compatibility

Chemask NA is generally compatible with most materials used in printed circuit board fabrication. As with any solder masking agent, compatibility with substrate should be determined on a non-critical area prior to use.

Application Method

Squeeze Bottle/Syringe	Yes
Spatula	Yes
Screening	Yes
Automatic Dispensing	Yes
Removal	By hand
Clean-up before curing	Use water

Usage Instructions

For industrial use only. Read SDS carefully prior to use.

Chemask NA solder masking agent is engineered for all electronic manufacturing applications. When applying by hand using squeeze bottle or spatula, insure that all areas of the pre-tinned hole are evenly covered on the side to be soldered. Automatic dispensing equipment may also be used as appropriate. Chemask NA may also be screen printed. Depending on ambient conditions, temporary mask may remain on assemblies for extended periods of time prior to processing.

REMOVAL: After allowing the Chemask NA to fully cure, the temporary mask can be removed by hand or using tweezers.

Availability

CM8	8 fl. oz. / 236 mL Liquid Squeeze Bottle
CM1	1 gal. / 3.7 L Liquid

Environmental Impact Data

CFC	0.0%
HCFC	0.0%
GWP	0.0%
VOC	0.0%
HFC	0.0%
ODP	0.00

CFC, HCFC, VOC, and HFC numbers shown are the content by weight. Ozone depletion potential (ODP) is determined in accordance with the Montreal Protocol and U.S. Clean Air Act of 1990. The ODP of this product is 0.0. It is the sum of the ODP of the substances that may contribute to the depletion of stratospheric ozone, based upon the weight of each substance in the product's formulation. Global warming potential (GWP) is calculated based on a 100 year time horizon. Carbon dioxide has a GWP of 1.

Technical and Application Assistance

Chemtronics provides a technical hotline to answer your technical and application related questions.

The toll free number is: 1-800-TECH-401.

Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.